

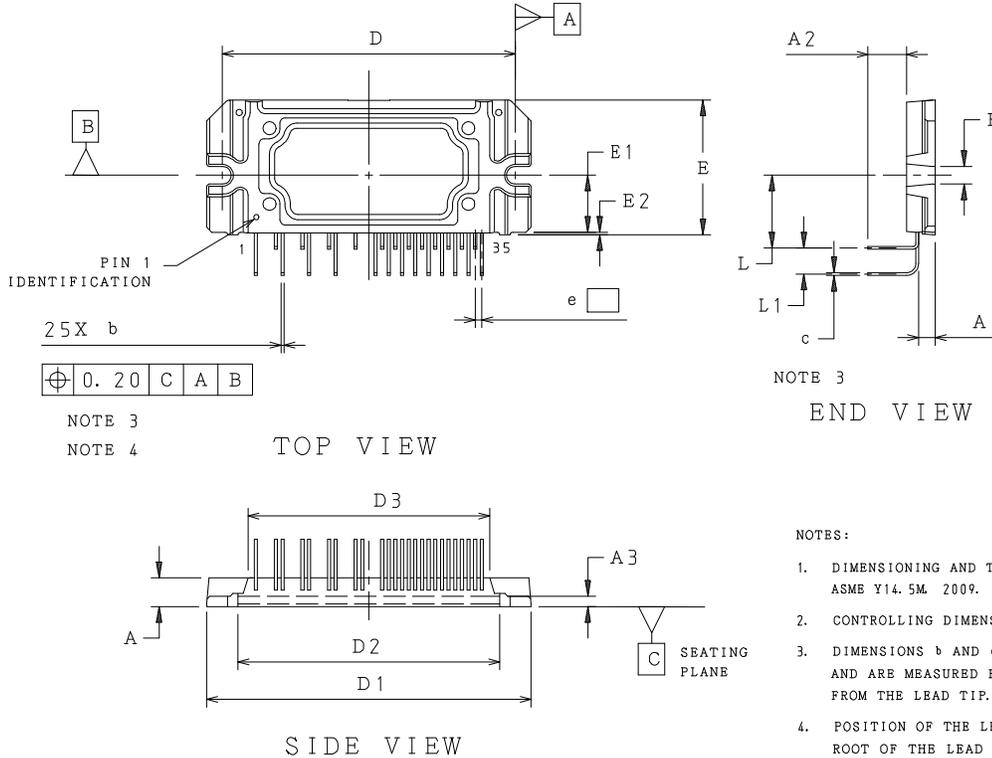
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®



SIP35 56x25.8 / SIP2A-3 CASE 127DY ISSUE O

DATE 07 APR 2016



DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	5.00	5.50	6.00
A1	2.70	3.20	3.70
A2	6.90	7.40	7.90
A3	1.50	2.00	2.50
b	0.55	0.60	0.80
c	0.45	0.50	0.70
D	55.50	56.00	56.50
D1	61.50	62.00	62.50
D2	49.50	50.00	50.50
D3	45.70	46.20	46.70
E	25.30	25.80	26.30
E1	10.90 REF		
E2	0.00	0.50	1.00
e	1.27 BSC		
F	2.90	3.40	3.90
L	13.40	13.90	14.40
L1	4.50	5.00	5.50

NOTE 3

END VIEW

NOTE 3

NOTE 4

TOP VIEW

SIDE VIEW

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSIONS b AND c APPLY TO THE PLATED LEAD AND ARE MEASURED BETWEEN 1.00 AND 2.00 FROM THE LEAD TIP.
4. POSITION OF THE LEADS IS DETERMINED AT THE ROOT OF THE LEAD WHERE IT EXITS THE PACKAGE BODY.
5. MIRROR SURFACE MARK INDICATES PIN 1 POSITION.
6. MISSING PINS ARE: 2, 3, 6, 7, 10, 11, 14, 15, 17, AND 18.

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